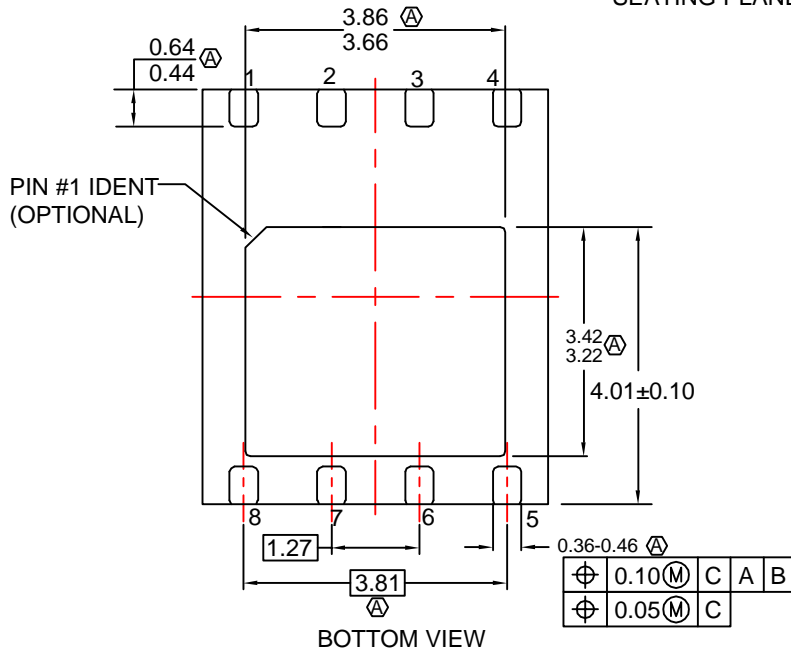
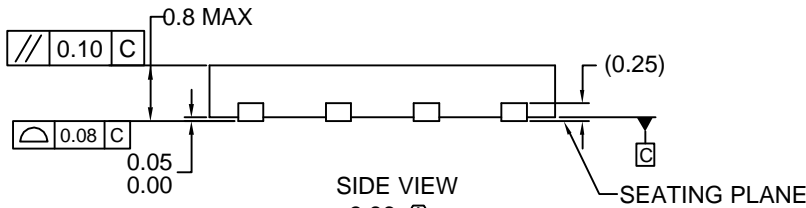
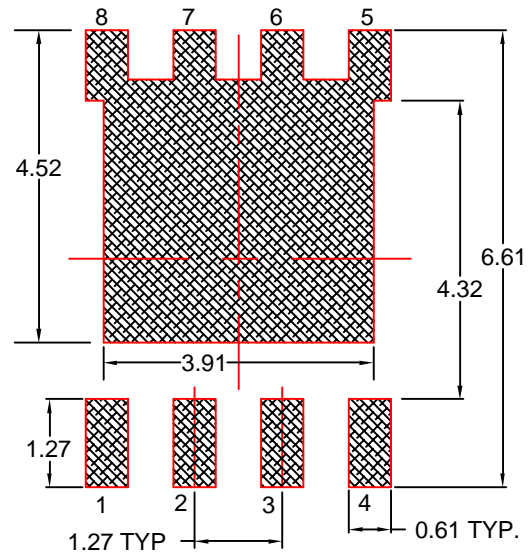
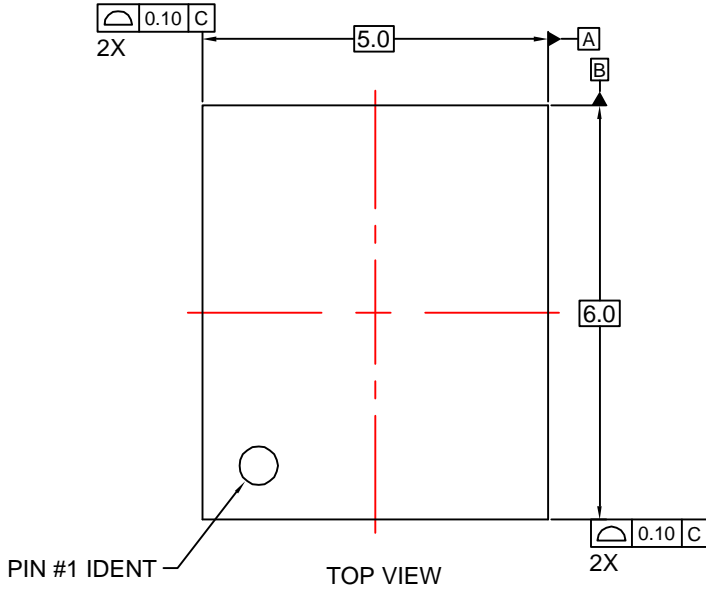


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REVISIONS				
LTR	DESCRIPTION	EDCN	DATE	BY/APPR
A	RELEASE TO DOCUMENT CONTROL	ECN-MKT-MLP08G	09-03-05	David
B	REVISE TO CORRECT DAP SIZE	ECN-MKT-MLP08G	08-06-05	David
C	I) REVISE TO CORRECT PKG THICKNESS II) REVISE THE PACKAGE PROFILE TOLERANCE	ECN-MKT-MLP08G	MARCH 21, 06	CHIP KING



**NOTES:**

- Ⓐ DOES NOT FULLY CONFORM TO JEDEC REGISTRATION, MO-229. DATED 11/2001.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- D. TERMINALS 5,6,7 AND 8 ARE TIED TO THE EXPOSED PADDLE

MLP08GrevC

APPROVALS		DATE	FAIRCHILD			
DRAWN	CHIP KING	21 MARCH 06	Bayan Lepas, FIZ, SEMICONDUCTOR, 11900, Penang, Malaysia.			
DFTG. CHK.	LY LIM	21 MARCH 06	8LD,MLP,DUAL,NON-JEDEC, 5X6 MM, TIED DAP			
ENGR. CHK.	DAVID CHONG	21 MARCH 06				
			SCALE	SIZE	DRAWING NUMBER	REV
			N/A	N/A	FSC-MKT-MLP08G	C
			DO NOT SCALE DRAWING		SHEET 1 of 1	